
Retraction notice

The Publisher of *Microelectronics International* wish to retract the article, “Packaging design and thermal analysis for 1 mm² high power VCSEL”, by Khairul Mohd Arshad, Muhamad Mat Noor, Asrulnizam Abd Manaf, Kawarada H., Falina S. and Syamsul M., published in *Microelectronics International*, Vol. 40, No. 1, <https://doi.org/10.1108/MI-03-2022-0048>.

It has come to our attention by the corresponding author that Figures 4, 5 and 8 were created by a third party and the

authors did not receive permission to use them in their manuscript.

The submission guidelines of *Microelectronics International* make it clear that prior to article submission, authors should ensure they have applied for, and received, written permission to use any material that has been created by a third party.

As this is considered a breach of copyright, Emerald has made the decision to retract the paper.

The publisher of the journal sincerely apologises to its readers.

The current issue and full text archive of this journal is available on Emerald Insight at: <https://www.emerald.com/insight/1356-5362.htm>



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